

APR 19 2007

Application No.: 10/603,924

Docket No.: JCLA7109-R

**In The Drawings:**

Please replace the pending drawings of FIGs. 2, 3 and 4 with the drawings attached hereto and labeled as "Replacement Sheets" in the top margin.

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REMARKS

Present Status of the Application

Applicants have noted with appreciation that claims 1, 2, 4-7 and 31-41 have been allowed.

To rectify several deficiencies in the claims and the drawings, Applicants have amended claims 1, 2, 5, 33-34 and 37-40 and the drawings by correcting the typographical errors therein, and hereby respectfully submit that no new matter is introduced. Particularly, the erroneous spellings appearing in claims 2, 5, 33-34 and 37-40 have been corrected, and claim 1 has been amended to more clearly define that the chemical-mechanical polishing process is performed to remove a portion of the layer on the silicon wafer.

It is believed that these amendments do not change the consideration of patentability and thus should be acceptable.

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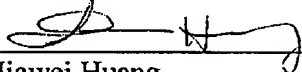
**CONCLUSION**

For at least the foregoing reasons, it is believed that all the pending claims 1, 2, 4-7 and 31-41 are in proper condition for allowance. If the Examiner believes that a telephone conference would expedite the examination of the above-identified patent application, the Examiner is invited to call the undersigned.

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Respectfully submitted,  
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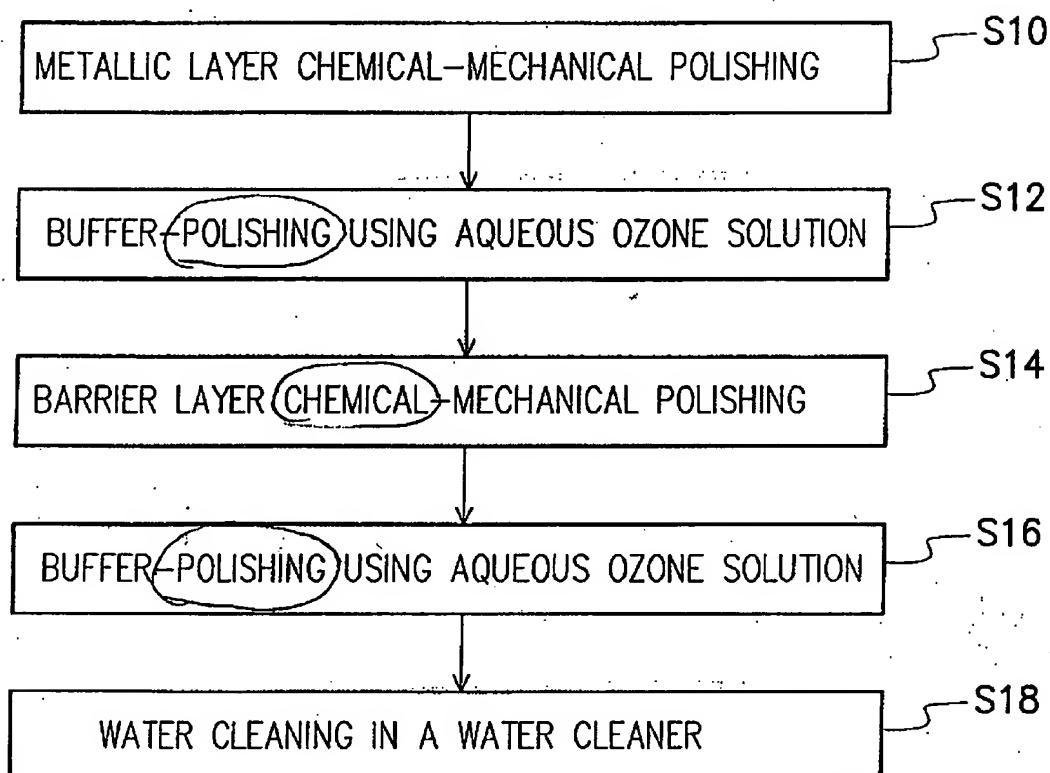
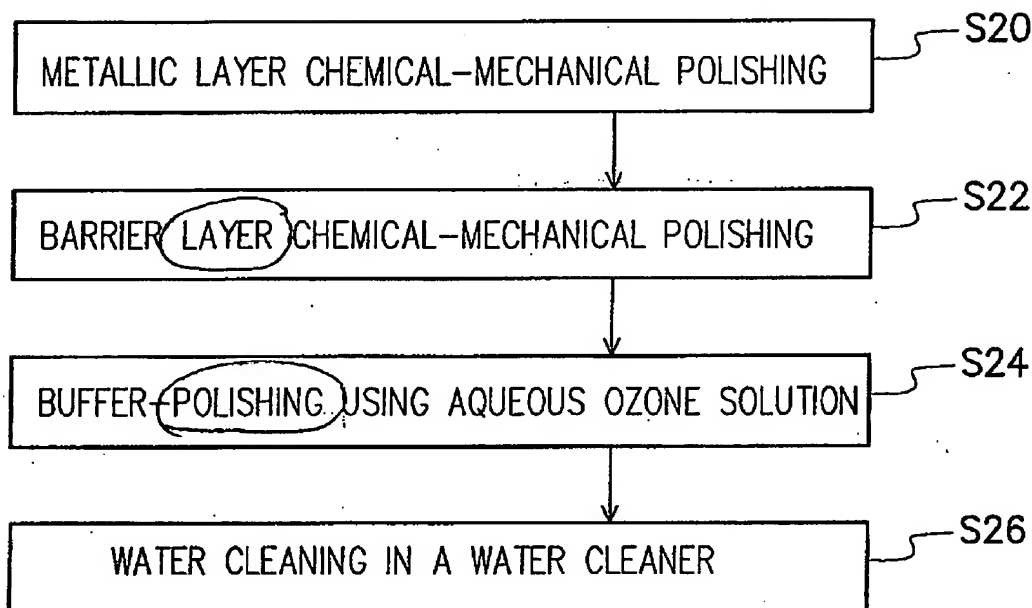
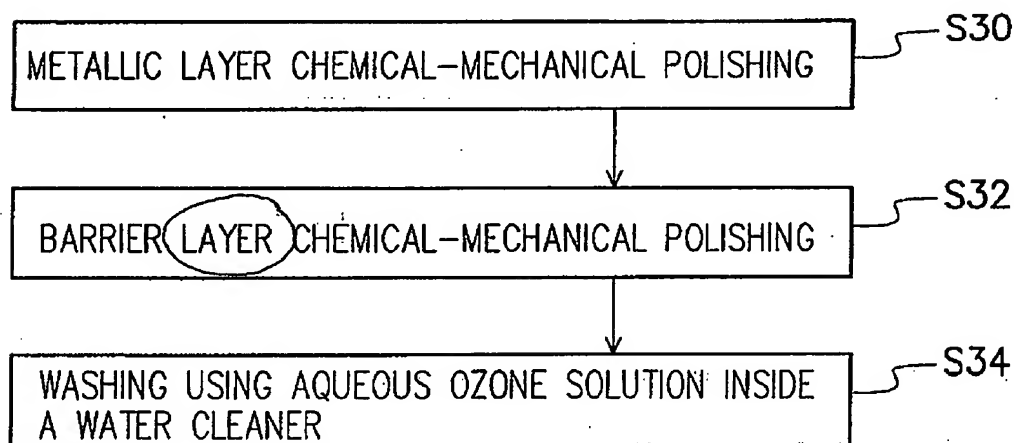
*Annotated Marked-up drawing*

FIG. 2

*Annotated Marked-up drawing***FIG. 3****FIG. 4**